

CLAIMS

- 1 1. A layer structure comprising :
 - 2 a semi-conductor heterostructure;
 - 3 at least one metallic interlayer deposited next to at least one surface
 - 4 and in at least one region of said heterostructure; and
 - 5 a dielectric layer coated next to said interlayer.
- 1 2. A layer structure according to claim 1 wherein only one surface is
- 2 deposited with said metallic interlayer.
- 1 3. A layer structure according to claim 1 wherein only the top surface is
- 2 deposited with said metallic interlayer.
- 1 4. A layer structure according to claim 1 further comprising an oxide
- 2 layer between said heterostructure and said interlayer.
- 1 5. A layer structure according to claim 2 further comprising an oxide
- 2 layer between said heterostructure and said interlayer.
- 1 6. A layer structure according to claim 2 wherein said heterostructure is a
- 2 single quantum well structure, and multiple quantum well structure, a
- 3 superlattice structure or a quantum dot structure.
- 1 7. A layer structure according to claim 2 wherein said heterostructure
- 2 comprises
- 3 a AlGaAs/GaAs quantum well structure having a plurality of alternating
- 4 AlGaAs and GaAs layers; or

5 an InGaAs/GaAs quantum well structure having a plurality of
6 alternating InGaAs and GaAs layers.

1 8. A layer structure according to claim 2 wherein said interlayer
2 comprises a single layer of metal, a single layer of alloyed metal,
3 multiple layers of metal, multiple layers of alloyed metal, or multiple
4 layers of metal and alloyed metal.

1 9. A layer structure according to claim 2 wherein said interlayer is 1 to
2 10,000 angstrom thick.

1 10. A layer structure according to claim 2 wherein said interlayer is 10 to
2 500 angstrom thick.

1 11. A layer structure according to claim 2 wherein a plurality of interlayers
2 are deposited in different regions of said heterostructure.

1 12. A layer structure according to claim 2 wherein a plurality of interlayers
2 are deposited in different regions of said heterostructure, and at least
3 two of said interlayers have different thicknesses.

1 13. A layer structure according to claim 2 wherein said dielectric layer is
2 made from silica oxide or silica.

1 14. A layer structure according to claim 5 wherein said heterostructure is a
2 single quantum well structure, and multiple quantum well structure, a
3 superlattice structure or a quantum dot structure.

1 15. A layer structure according to claim 5 wherein said heterostructure
2 comprises

- 3 a AlGaAs/GaAs quantum well structure having a plurality of alternating
4 AlGaAs and GaAs layers; or
- 5 an InGaAs/GaAs quantum well structure having a plurality of
6 alternating InGaAs and GaAs layers.
- 1 16. A layer structure according to claim 5 wherein said interlayer
2 comprises a single layer of metal, a single layer of alloyed metal,
3 multiple layers of metal, multiple layers of alloyed metal, or multiple
4 layers of metal and alloyed metal.
- 1 17. A layer structure according to claim 5 wherein said interlayer is 1 to
2 10,000 angstrom thick.
- 1 18. A layer structure according to claim 5 wherein said interlayer is 10 to
2 500 angstrom thick.
- 1 19. A layer structure according to claim 5 wherein a plurality of interlayers
2 are deposited in different regions of said heterostructure.
- 1 20. A layer structure according to claim 5 wherein a plurality of interlayers
2 are deposited in different regions of said heterostructure, and at least
3 two of said interlayers have different thicknesses.
- 1 21. A layer structure according to claim 5 wherein said heterostructure is
2 made from elements from column III to V of the periodic table of
3 elements.
- 1 22. A layer structure according to claim 5 wherein said dielectric layer is
2 made from silica oxide or silica.

- 3 a) forming an oxide layer on the top-surface of said
4 heterostructure;

5 b) masking said heterostructure with a mask of a predetermined
6 pattern such that said heterostructure is exposed in unmasked
7 regions;

8 c) depositing at least one metallic interlayer on said unmasked
9 regions;

10 d) lifting-off said mask;

11 e) post-annealing said dielectric layer onto said heterostructure.

1 26. A method according to claim 25 wherein steps (c) and (d) are
2 repeated to produce additional interlayers according to additional
3 specific patterns.

1 27. A layer structure comprising :
2 a semi-conductor heterostructure;
3 at least one oxide layer formed on at least one surface of said
4 heterostructure; and
5 a dielectric layer coated next to said oxide layer.

1 28. A layer structure according to claim 27 wherein said oxide layer is
2 formed by the oxidation of said surface of said heterostructure.